

L Number	Hits	Search Text	DB	Time stamp
1	2139	(dmd or (digital adj micro adj mirror adj device))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/27 15:25
3	1590	(dmd or (digital adj micro adj mirror adj device)) and (method or process or manufacture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/27 15:36
4	37	(dmd or (digital adj micro adj mirror adj device)) and wafer and (chip same mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/27 15:37
2	69	(dmd or (digital adj micro adj mirror adj device)) and (metal\$ with (wafer or chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/27 16:59
5	8330	mirror with (wafer or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/27 17:00
6	1507	(mirror with (wafer or chip)) and @pd>20001005	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/27 17:02
7	300	(mirror with (wafer or chip)) and (pad with chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/27 17:03
8	434	(dmd or (digital adj micro adj mirror adj device)) and (diec or singulate or cut or break)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/27 17:05
9	46	((dmd or (digital adj micro adj mirror adj device)) and (diec or singulate or cut or break)) and photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/27 17:05
10	6	((dmd or (digital adj micro adj mirror adj device)) and (diec or singulate or cut or break)) and (remove with photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/27 17:05